



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN165001

Date: December 14, 2016

Subject: Qualification of BOM Change for Select 32-lead TSOP Products at OSE-Taiwan

To: JAMIE PEDERSON
DIGIKEY
digiKey.supplierInfo@digkey.com

Change Type: Major

Description of Change:

Cypress announces the qualification of roughened PPF (pre-plated frame) leadframe, Sumitomo CRM-1076WA die attach epoxy, and Sumitomo G700L mold compound with plasma process prior to mold at assembly subcontractor OSE Taiwan on select 32-lead TSOP Automotive package.

New shipments of the affected part numbers assembled from OSE Taiwan will use the following shaded bill of materials (BOM):

Material	Current Bill of Materials (OSE Taiwan)	New Bill of Materials (OSE Taiwan)
Mold Compound	Hitachi CEL-9200	Sumitomo G700L
Die Attach Epoxy	Hitachi EN-4900G	Sumitomo CRM-1076WA
Bond Wire	1.0 mil Au	1.0 mil Au
Leadframe	Standard PPF (pre-plated frame)	Roughened PPF (pre-plated frame)
Lead Finish	NiPdAu	NiPdAu

There are no changes to ordering part numbers. Product datasheets remain the same and can be downloaded from the Cypress Website (www.cypress.com).

Benefit of Change:

The qualification of the new epoxy, leadframe and mold compound material with plasma process prior to mold at OSE Taiwan will allow Cypress to provide better field reliability and continuity of supply. This in turn provides the means for Cypress to continue to meet customers' varied packaging needs as well as delivery commitments in dynamic, changing market conditions.

Part Numbers Affected: 4

Affected Parts: See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

This new epoxy, leadframe and mold compound material with plasma process prior to mold has been qualified through a series of tests identified in the Qualification Test Plan (QTP) Report No. 154605. This qualification report can be found as an attachment to this notification.

Sample Status:

Qualification samples are not built ahead of time for all part numbers affect by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated sample ordering part numbers. Sample requests for products without samples built ahead of time will be built to order and subject to standard lead times. Please contact your Sales Representative as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

This change will be effective upon customer approval.

Anticipated Impact:

None anticipated. Products manufactured are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

There will be no changes to the part number. Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item	Marketing Part Number	Sample Ordering Part Number
1	CY7C1019CV33-10ZXA	CY7C1019CV33-10ZXAKO
2	CY7C1019CV33-10ZXAT	CY7C1019CV33-10ZXAKO
3	CG8220AA	CY7C1019CV33-10ZXAKO
4	CG8220AAT	CY7C1019CV33-10ZXAKO